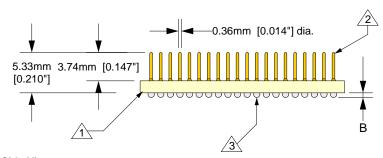


Top View (reference only)



Side View (reference only)

Note: SMT foot is independent of actual BGA package thickness.

1

Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. Non-clad.



Pins: material- Brass Alloy 360 1/2 hard; finish-0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).



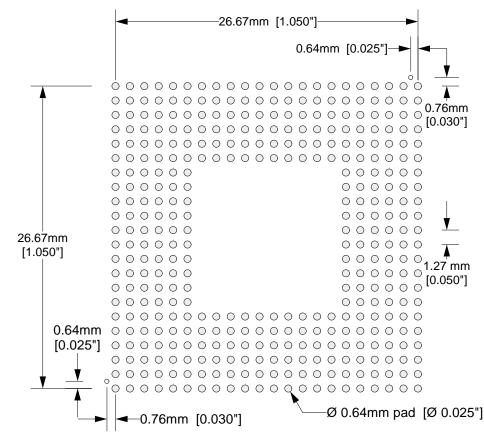
Balls: Eutectic 63/37 SnPb. Thermally isolated from terminal pins

Description: BGA Emulator Foot (SM base).

384 position terminal pins (MGA, Mini-grid Array) to solder balls. Surface mounts to target BGA land pattern.

F					
	SF-BGA384A-B-11 Drawing	Status: Released	Scale	-	Rev: A
3	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: B. Roux		Date:10/21/04	
		File: SF-BGA384A-B-11 Dwg.mcd		Modified:	
		•		•	

Package Code: BGA384A



Top View: Recommended PCB Layout

Scale: 3:1

Pin Count	384	
Array Size	22 x 22	
Pitch	1.27 mm[0.050"]	
Perimeter size (XxY)	29.0mm[1.142"] x 29.0mm[1.142"]	
MGA Location (CxD)	1.17mm[0.046"] x 1.17mm[0.046"]	
Ball Thickness (B)	0.61mm[0.024"]	

Tolerances: diameters ± 0.03 mm [± 0.001 "], PCB perimeters ± 0.13 mm [± 0.005 "], PCB thicknesses ± 0.18 mm [± 0.007 "], pitches (from true position) ± 0.08 mm [± 0.003 "], all other tolerances ± 0.13 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.